Tacky-Free Epoxy Film
Electrical Conductive Adhesive
Moisture-Temperature Resistant
-60 Tg : Flexible "Stress-Free"

IDEAL FOR:
- Large Area Die Attach
- Mismatched CTE Substrate Attach
- Electrical & Thermal Ground Plane Bonding
- Wafer Lamination and Stack-chip Bonding

DESCRIPTION:
ESP8450-WL is a high melt-flow version of standard ESP8450 designed for large area bonding and wafer-level lamination for stack-chip applications. It is a solvent resistant, silver-filled, flexible epoxy film adhesive designed for bonding die, component and substrate to a mismatched substrate or carrier. This novel, B-staged electrically conductive adhesive offers excellent flexibility from -55°C to 150°C. The dry, tack-free handling of the film makes it ideal for an automated pick and place assembly and is reworkable from 80°C to 150°C.

ESP8450-WL has excellent thermal conductivity and its low Tg adhesive imposes minimum thermal stress on bonded parts during thermal cycling or shock testing.

AVAILABILITY:
ESP8450-WL is available in sheet sizes or as custom preforms. Standard thicknesses are 0.003" and 0.006". Special thicknesses are available.

APPLICATION PROCEDURES:
(1) Let product stay at room temperature for 15 minutes. Remove film from protective paper.
(2) Cut to desired size.
(3) Place on substrate and cure according to one of the recommended schedules.

The die or component can also be tacked on the substrate at 100°C or higher with nominal placement pressure. When a fillet around the edge of the die or component is observed, the pressure can be released for the rest of the bonding cycle.

SHELF LIFE:
- Storage temperature: 0-5°C
- Shelf Life: 1 yr
- in sealed container

CAUTION: This product may cause skin irritation. Avoid skin contact. If contact does occur, wash immediately with soap and water. Please refer SDS for more details.

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